

## General Description

SFGMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially optimized for synchronous rectification systems with low driving voltage.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

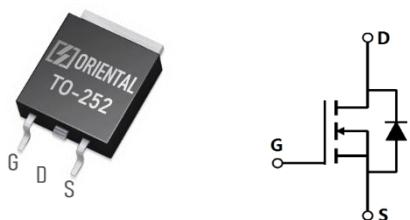
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	80	V
$I_D, pulse$	120	A
$R_{DS(ON), max} @ V_{GS}=10V$	16	mΩ
$Q_g$	22.5	nC

## Marking Information

Product Name	Package	Marking
SFG08R16DF	TO252	SFG08R16D

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	80	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	40	A
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	120	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_S$	40	A
Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{S, \text{pulse}}$	120	A
Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$	$P_D$	72	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	20	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.7	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	80			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		13.0	16.0	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=10 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		16.0	20.0	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=7 \text{ A}$
Gate-source leakage current	$I_{GSS}$			100	$\text{nA}$	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=80 \text{ V}, V_{GS}=0 \text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		1432.2		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		343.6		pF	
Reverse transfer capacitance	C <sub>rss</sub>		9.1		pF	
Turn-on delay time	t <sub>d(on)</sub>		18.9		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =10 A
Rise time	t <sub>r</sub>		4.6		ns	
Turn-off delay time	t <sub>d(off)</sub>		38.1		ns	
Fall time	t <sub>f</sub>		18.9		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		22.5		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, I <sub>D</sub> =10 A
Gate-source charge	Q <sub>gs</sub>		4.1		nC	
Gate-drain charge	Q <sub>gd</sub>		5.4		nC	
Gate plateau voltage	V <sub>plateau</sub>		3.1		V	

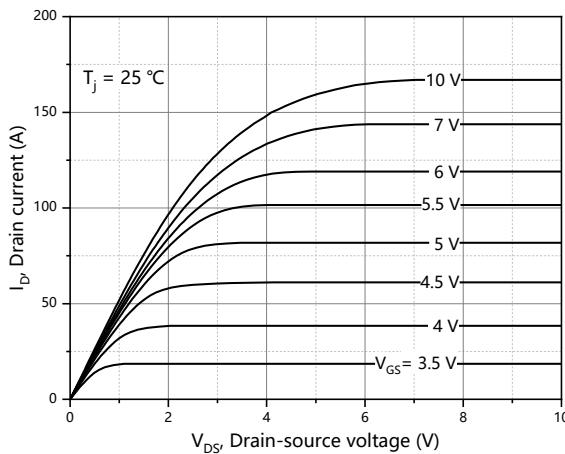
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>s</sub> =10 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		53.0		ns	
Reverse recovery charge	Q <sub>rr</sub>		91.1		nC	
Peak reverse recovery current	I <sub>rrm</sub>		2.9		A	

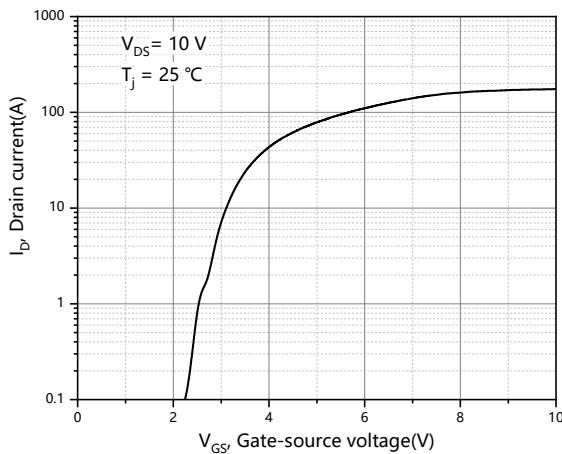
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

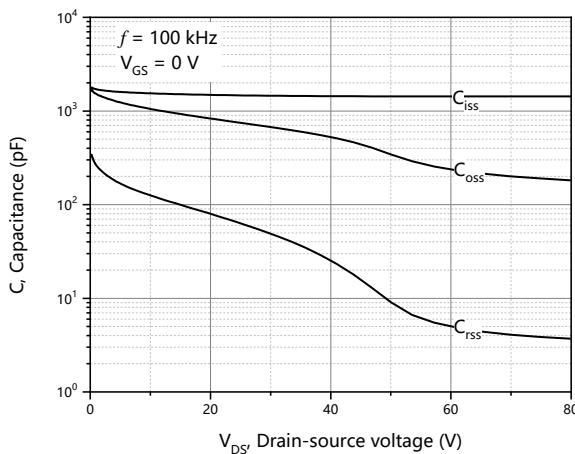
## Electrical Characteristics Diagrams



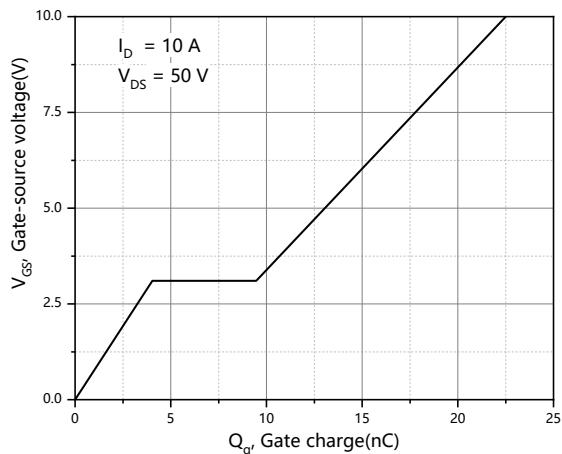
**Figure 1. Typ. output characteristics**



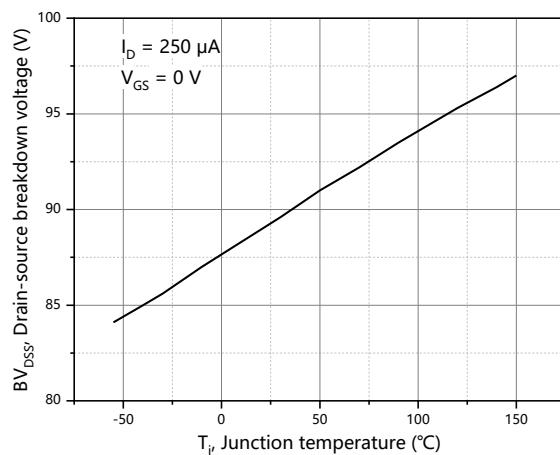
**Figure 2. Typ. transfer characteristics**



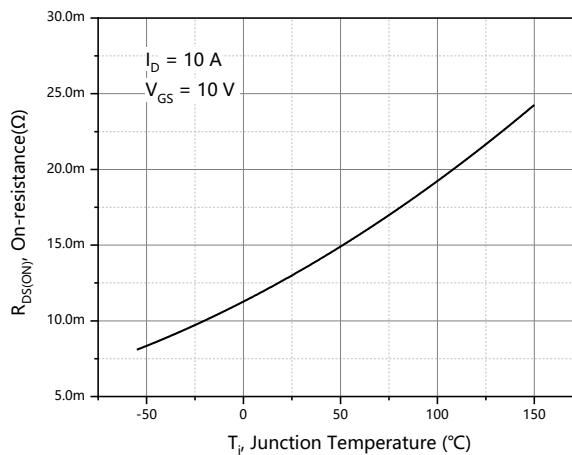
**Figure 3. Typ. capacitances**



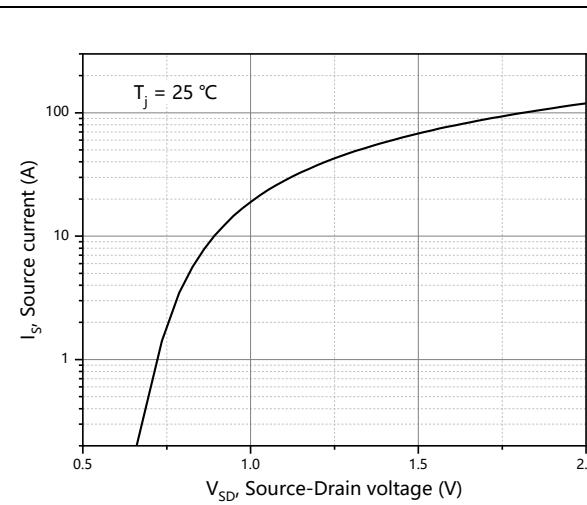
**Figure 4. Typ. gate charge**



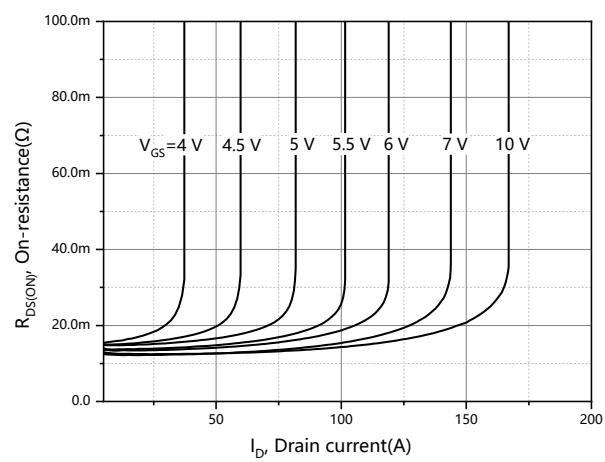
**Figure 5. Drain-source breakdown voltage**



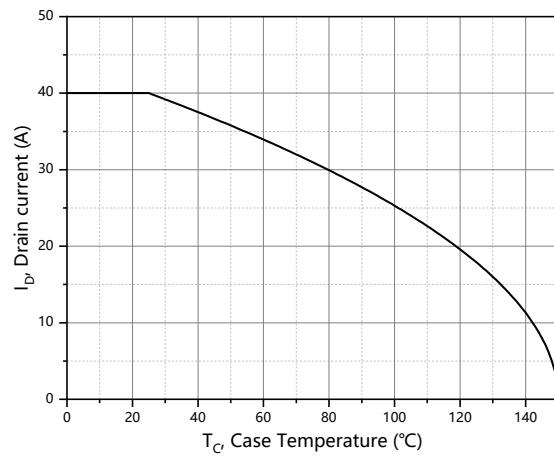
**Figure 6. Drain-source on-state resistance**



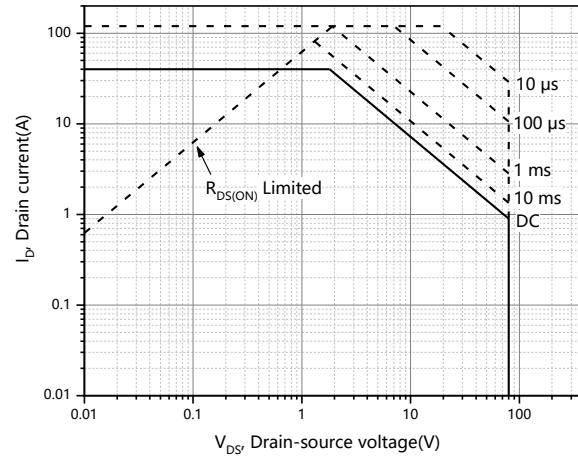
**Figure 7. Forward characteristic of body diode**



**Figure 8. Drain-source on-state resistance**

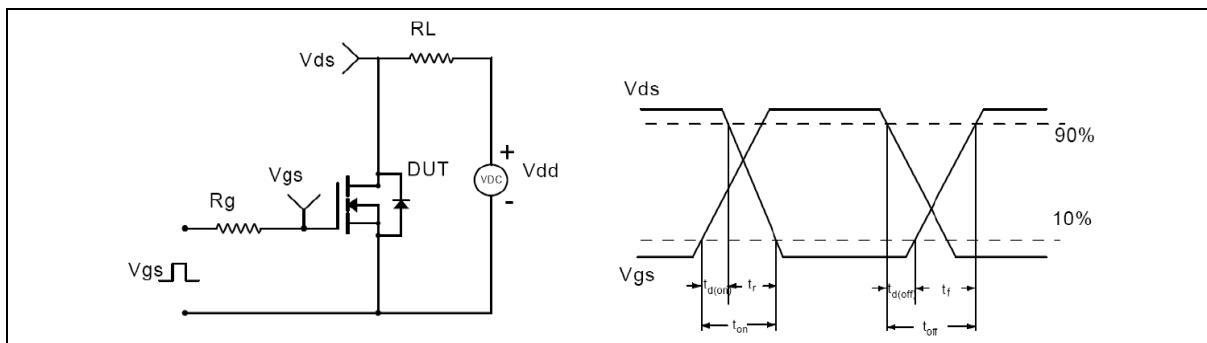
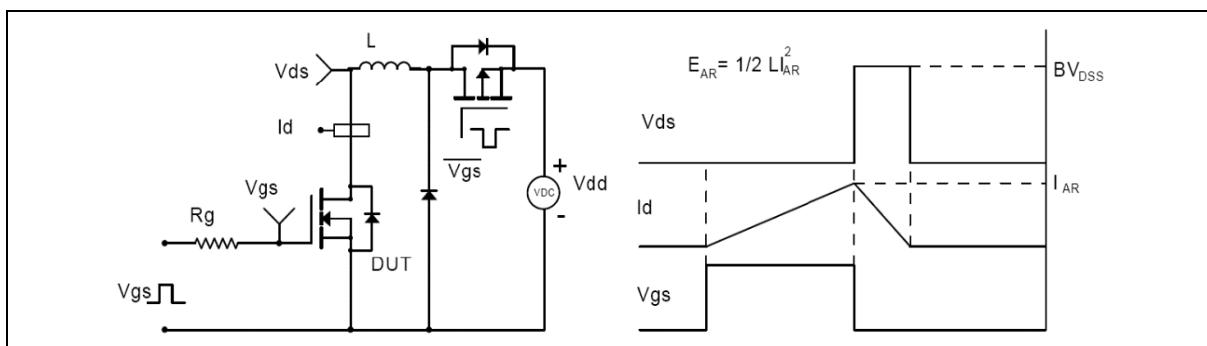


**Figure 9. Drain current**



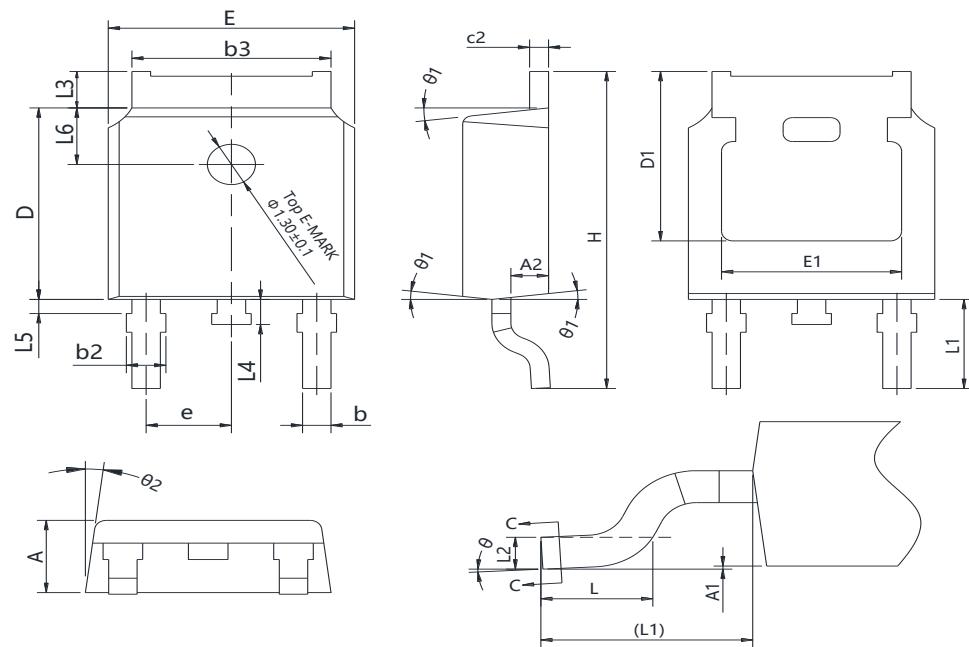
**Figure 10. Safe operation area T<sub>C</sub>=25 °C**

**Test circuits and waveforms**

**Figure 1. Gate charge test circuit & waveform**

**Figure 2. Switching time test circuit & waveforms**

**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**

**Figure 4. Diode reverse recovery test circuit & waveforms**

### Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.38
A1	0.00	-	0.10
A2	0.90	1.01	1.10
b	0.72	-	0.85
b1	0.71	0.76	0.81
b2	0.72	-	0.90
b3	5.13	5.33	5.46
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	0.47	-	0.60
D	6.00	6.10	6.20
D1	5.25	-	-
E	6.50	6.60	6.70
E1	4.70	-	-
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.508BSC		
L3	0.90	-	1.25
L4	0.60	0.80	1.00
L5	0.15	-	0.75
L6	1.80REF		
$\theta$	0°	-	8°
$\theta_1$	5°	7°	9°
$\theta_2$	5°	7°	9°

Version 1: TO252-J package outline dimension

## Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO252-J	2500	2	5000	5	25000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG08R16DF	TO252	yes	yes	yes

## Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives ([www.orientalsemi.com](http://www.orientalsemi.com)).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved /